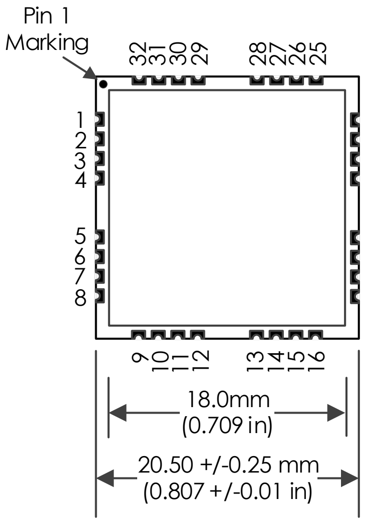
QFN150P2050x2050x330-32 Package Details

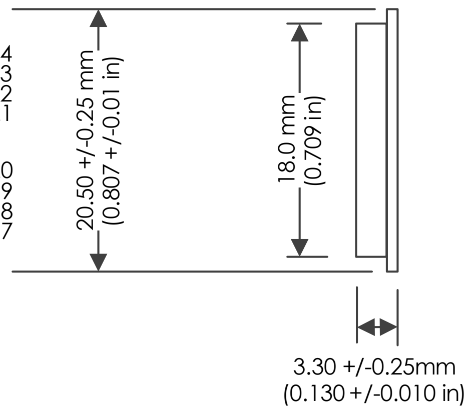
Metal 20.5mm 32 Lead QFN

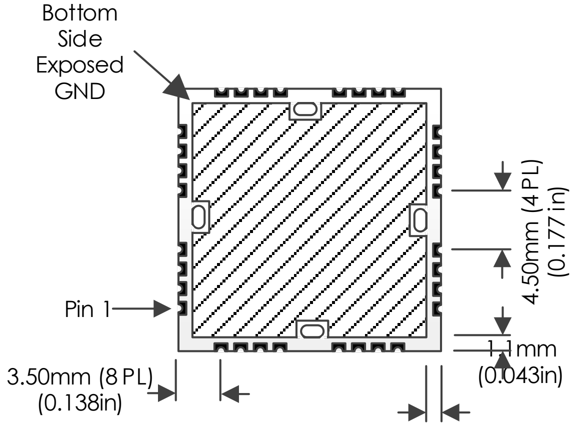
Package Drawing

Top View



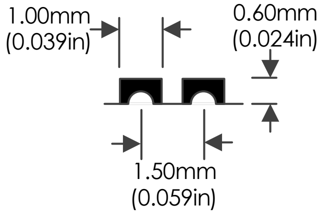
Side View





Bottom View

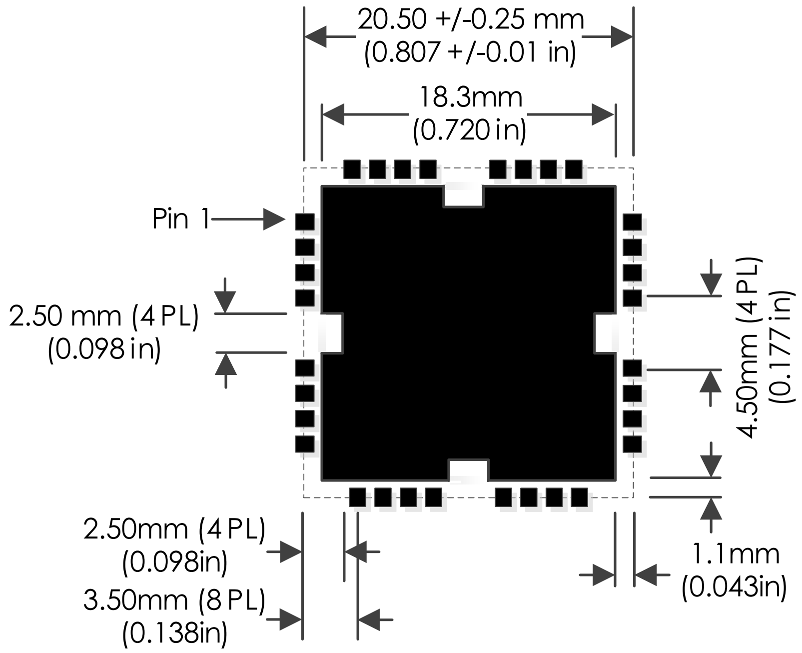
Pad and Spacing Detail



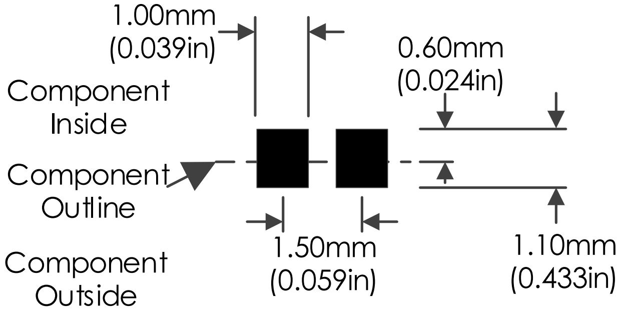
Notes:

1.All dimensions shown are in mm
2. Substrate material: Isola370HR
3. Lid material: Nickel Silver alloy
4. Lead finish: ENEPIG
Ni: 3.00 um minimum
Pd: 0.05 um minimum
Au: 0.05 um minimum

Recommended Footprint



Pad and Spacing Detail



Recommended Assembly Procedure

It is recommended to attach the bottom side ground pad to the printed circuit board using a highly conductive silver epoxy and then hand solder the 32 pins along the part's perimeter to their intended printed circuit board pads using lead-free solder.

The recommended silver epoxy is MG Chemicals part 8331S and the recommended assembly thickness is 3 to 5 mils.

If the device is to be attached (both the ground pad and perimeter pins) to the circuit board using a typical lead-free solder reflow process reaching temperatures of 260C, the excessive temperature can cause internal parts to the filter bank to reflow and result in damage to the device. If a solder reflow process must be used, it is recommended to use a lower temperature leaded solder profile, typically 225C maximum.

Package Naming Convention

QFN	–	Quad Flat No-Lead
150	–	Pitch = 1.50mm
2050	–	Body Width = 20.50mm
2050	–	Body Length = 20.50mm
330	–	Height = 3.30mm
32	–	Pin Quantity

*Based on IPC-7351B naming convention

Revision History

Date	Revision Number	Notes
April 8, 2020	1	Initial Release